



S/N 10/023819

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Biju Chandran et al.	Examiner:	John Vigushin
Serial No.:	10/023819	Group Art Unit:	2827
Filed:	December 21, 2001	Docket:	884.A27US1
Title:	CHIP-JOIN PROCESS TO REDUCE ELONGATION MISMATCH BETWEEN THE ADHERENTS AND SEMICONDUCTOR PACKAGE MADE THEREBY		
Assignee:	Intel Corporation	Customer No:	21186

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Applicants note that certain of the enclosed references were first received in a communication from a foreign patent office in a counterpart foreign application. A copy of the relevant International Search Report, in PCT/IS02/36038, is also enclosed.

Pursuant to 37 C.F.R. §1.97(b), it is believed that no fee or statement is required with the Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Information Disclosure Statement considered.

INFORMATION DISCLOSURE STATEMENT

Serial No : 10/023819

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Title: CHIP-JOIN PROCESS TO REDUCE ELONGATION MISMATCH BETWEEN THE ADHERENTS AND SEMICONDUCTOR
PACKAGE MADE THEREBY

Assignee: Intel Corporation

Page 2

Dkt: 884.A27US1 (INTEL)

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

BIJU CHANDRAN ET AL.

By their Representatives,

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Date March 18, 2004 By Ann M. McCrackin
Ann McCrackin
Reg. No. 42,858

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being hand-delivered to: US Patent and Trademark Office, 2011 South Clark Place, Customer Window, **Mail Stop 313(c)**, Crystal Plaza Two, Lobby, Room 1B03, Arlington, VA 22202, on this 19TH day of March, 2004.

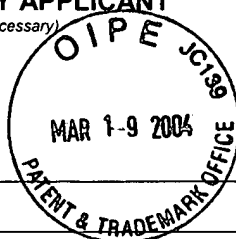
Larry J. Hecker
Name

Larry J. Hecker
Signature

Substitute for form 1449A/PTO

**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

(Use as many sheets as necessary)



Complete if Known

Application Number	10/023819
Filing Date	December 21, 2001
First Named Inventor	Chandran, Biju
Group Art Unit	2827
Examiner Name	Vigushin, John

Sheet 1 of 1

Attorney Docket No: 884.A27US1

US PATENT DOCUMENTS

Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate
	US-3,871,015	03/11/1975	Lin, Paul T.C., et al.	357	67	08/14/1969
	US-4,481,403	11/06/1984	Del Monte, Lou A.	219	209	03/04/1983
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	US-6,170,155	01/09/2001	Marion, F. , et al.	29	840	05/15/1997
	US-6,259,155	07/10/2001	Interrante, Mario J., et al.	257	690	04/12/1999
	US-6,310,403	10/30/2001	Zhang, C. , et al.	257	786	08/31/2000
	US-6,330,967	12/18/2001	Milewski, Joseph M., et al.	228	180.22	03/13/1997
	US-6,395,124	05/28/2002	Oxman, J. D., et al.	156	275.5	07/30/1999

FOREIGN PATENT DOCUMENTS

Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T ²
	JP-08-332590	12/17/1996	Bitailou, A. , et al.	B23K	35/22	
	JP-09-275107	10/21/1997	Ozoe, Shoji	H01L	21/321	
	JP-10-12659	01/16/1998	Yamamoto, Michihiko	H01L	21/60	
	JP-59-177957	10/08/1984	Kano, Hiroshi , et al.	H01L	23/48	

OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
		ANONYMOUS, "Solder ball for semiconductor chip - has height increased so that stress caused by difference in thermal expansion between chip and substrate is minimised", <u>Research Disclosure RD-291011</u> , Derwent 1988-255069, (7/10/88), 2 pages	

EXAMINER**DATE CONSIDERED**